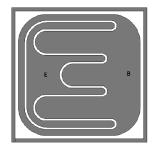


### NPN Low Power Silicon Transistor Die

#### Features

- Qualified to MIL-PRF-19500/391
- Lightweight & Low Power
- Ideal for Space, Military, & Other High Reliability Applications



## Electrical Characteristics ( $T_A = +25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Units	Min.	Max.
Collector - Emitter Breakdown Voltage	I <sub>C</sub> = 30 mA	V <sub>(BR)CEO</sub>	V dc	80	—
Collector - Base Cutoff Current	V <sub>CB</sub> = 140 V	I <sub>CBO1</sub>	µA dc	—	10
Emitter - Base Cutoff Current	V <sub>EB</sub> = 7 V	I <sub>EBO1</sub>	µA dc	—	10
Collector - Emitter Cutoff Current	V <sub>CE</sub> = 90 V	I <sub>CES1</sub>	nA dc	_	10
Emitter - Base Cutoff Current	V <sub>EB</sub> = 5 Vdc I <sub>EBC</sub>		nA dc	—	10
Forward Current Transfer Ratio		h <sub>FE1</sub> h <sub>FE2</sub> h <sub>FE3</sub> h <sub>FE4</sub> h <sub>FE5</sub>	-	100 50 90 50 15	300 300 300
Collector - Emitter Saturation Voltage	$I_{C}$ = 150 mA; $I_{B}$ = 15 mA $I_{C}$ = 500 mA; $I_{B}$ = 50 mA	V <sub>CE(SAT)1</sub> V <sub>CE(SAT)2</sub>	V dc		0.2 0.5
Base - Emitter Saturation Voltage	I <sub>C</sub> = 150 mA; I <sub>B</sub> = 15 mA	$V_{\text{BE(SAT)}}$	V dc	_	1.1
Collector - Emitter Cutoff Current	T <sub>A</sub> = +150°C V <sub>CE</sub> = 90 V	I <sub>CES2</sub>	µA dc	_	5
Forward Current Transfer Ratio	$T_A = -55^{\circ}C$ V <sub>CE</sub> = 10 V dc; I <sub>C</sub> = 150 mA dc	h <sub>FE6</sub>		40	

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### NPN Low Power Silicon Transistor Die

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Parameter	Test Conditions	Symbol	Units	Min.	Max.		
Dynamic Characteristics							
Small-Signal Short-Circuit Forward -Current Transfer Ratio	$V_{CE}$ = 5 V dc; I <sub>C</sub> = 1 mA dc; f = 1 kHz	h <sub>FE</sub>		80	400		
Magnitude of Small-Signal Short-Circuit Forward Current Transfer Ratio	$V_{CE}$ = 10 V dc; I <sub>C</sub> = 50 mA dc; f = 20 MHz	h <sub>FE</sub>		5	20		
Input Capacitance (Output Open Circuited)	$V_{EB}$ = 0.5 V dc; I <sub>C</sub> = 0; 100 kHz ≤ f ≤ 1 MHz	C <sub>ibo</sub>	pF	_	60		
Open Circuit Output Capacitance	V <sub>CB</sub> = 10 V dc; I <sub>E</sub> = 0; 100 kHz ≤ f ≤ 1 MHz	$C_{obo}$	pF	—	12		
Noise Figure	$V_{CE}$ = 10 V dc; I <sub>C</sub> = 100 µA dc; Rg = 1 kΩ; power bandwidth = 200 H <sub>Z</sub> f = 1 kHz	NF	dB	_	4		
Pulse Response	See Figure 21 of MIL-PRF-19500/391	t <sub>on</sub> +t <sub>off</sub>	ns		30		

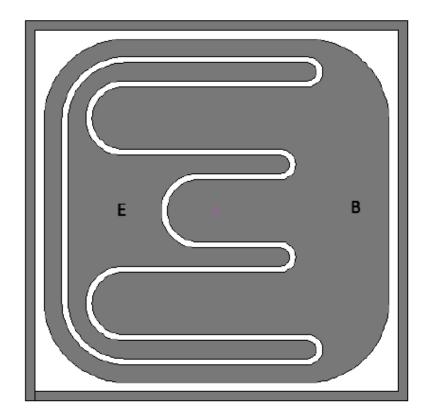
### Absolute Maximum Ratings ( $T_A = +25^{\circ}C$ unless otherwise specified)

Ratings	Symbol	Value	
Collector - Emitter Voltage	V <sub>CEO</sub>	80 V dc	
Collector - Base Voltage	V <sub>CBO</sub>	140 V dc	
Emitter - Base Voltage	$V_{\text{EBO}}$	7 V dc	
Collector Current	Ι <sub>C</sub>	1 A dc	
Operating & Storage Temperature Range	$T_J, T_{STG}$	-65°C to +200°C	



### NPN Low Power Silicon Transistor Die

**Outline Drawing (Die)** 



Physical characteristics (C-version):

- Die size:
- Die thickness:
- .023 x .023 inch ±.002 inch (0.584 X 0.584 ±0.051 millimeter). .010 inch ±.002 inch (0.254 ±0.508 millimeter).
- Base pad:
- B = .004 inch x .010 inch (0.102 X 0.254 millimeter).
- Emitter pad:
- E = .0039 inch x .0039 inch (0. 992 X 0.099 millimeter). Backside.
- Collector pad:
  Top metal:
- Aluminum 16,000Å minimum, 20,000Å nominal. Gold: 5,000Å ±500Å.
- Backside metal:

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#### NPN Low Power Silicon Transistor Die

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